

Kyung-yeol Kim

List of Publications by Year in descending order

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papers

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2258059

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#	ARTICLE	IF	CITATIONS
1	Environmental Reliability Evaluation of the Ultrasonic Bonded Metal with High- Temperature Test. , 2022, , .		0
2	RF Characterization in Range of 18GHz in Fan-out Package Structure Molded by Epoxy Molding Compound with EMI Shielding Property. , 2022, , .		2
3	Effects of Cu Opening Size on the Mechanical Properties of Epoxy-Contained Sn-58Bi Solder Joints. Journal of Nanoscience and Nanotechnology, 2019, 19, 6437-6443.	0.9	0
4	The Effect of Environmental Test on the Shear Strength of the Ultrasonic bonded Cu Terminal for Power Module. Journal of Welding and Joining, 2019, 37, 1-6.	1.3	1
5	Mechanical Property of SAC305 Ball-Grid Array and Epoxy Sn-58Bi Solder Joints with 85 Å°C/85% Relative Humidity Environmental Conditions. Journal of Nanoscience and Nanotechnology, 2018, 18, 6162-6166.	0.9	1
6	Effect of Epoxy on Mechanical Property of SAC305 Solder Joint with Various Surface Finishes Under 3-Point Bend Test. Journal of Nanoscience and Nanotechnology, 2018, 18, 6316-6320.	0.9	4
7	Microstructures and Drop Impact Test of SAC305, Sn58%Bi and Epoxy Sn58%Bi Solder Joint on the OSP Surface Finished PCB Substrate. Journal of Welding and Joining, 2018, 36, 14-20.	1.3	3
8	The reliability of ultrasonic bonded Cu to Cu electrode for 3D TSV stacking. Journal of Materials Science: Materials in Electronics, 2017, 28, 16467-16475.	2.2	6
9	Effect of Sodium Dodecylbenzene Sulfonate Contents on Oxide Behavior in Cu Nanopaste. Journal of Nanoscience and Nanotechnology, 2017, 17, 7497-7501.	0.9	0
10	Drop Reliability of Epoxy-contained Sn-58Åwt.%Bi Solder Joint with ENIG and ENEPIG Surface Finish Under Temperature and Humidity Test. Journal of Electronic Materials, 2016, 45, 3651-3658.	2.2	27